CLAIMS

1. A thermally conductive paste used for a die-attach material comprising:

a thermosetting resin;

a curing agent;

an acrylic compound; and

a thermally conductive filler,

wherein at least one of the thermosetting resin and the curing agent contains a resin having a biphenyl skeleton, the resin having a biphenyl skeleton contains a phenol resin having a biphenyl skeleton, the acrylic compound contains a (meth)acrylic monomer, and the thermosetting resin contains an epoxy resin.

2. The thermally conductive paste according to claim 1,

wherein the thermally conductive paste is used for an adhesion layer for bonding a substrate and an electronic component.

3. The thermally conductive paste according to claim 1 or 2,

wherein a viscosity of the thermally conductive paste is 10 Pa·s or more and 10^3 Pa·s or less, which is measured using a Brookefield viscometer at 25°C.

4. The thermally conductive paste according to any one of claims 1 to 3,

wherein the thermally conductive filler contains a metal, an oxide, or a nitride.

5. The thermally conductive paste according to any one of claims 1 to 4,

wherein the thermally conductive filler contains one or more

selected from the group consisting of silver, copper, and alumina.

6. The thermally conductive paste according to any one of claims 1 to 5,

wherein an average particle size D_{50} of the thermally conductive filler is 0.1 μm or more and 10 μm or less, which is measured by a laser diffraction scattering method.

7. The thermally conductive paste according to any one of claims 1 to 6,

wherein a 95% cumulative particle size D_{95} of the thermally conductive filler is 1 μm or more and 15 μm or less, which is measured by a laser diffraction scattering method.

8. The thermally conductive paste according to any one of claims 1 to 7,

wherein an amount of the thermally conductive filler is 50 mass% or more and 88 mass% or less with respect to the entire thermally conductive paste.

9. The thermally conductive paste according to any one of claims 1 to 8,

wherein the thermally conductive paste does not contain a solvent.

10. The thermally conductive paste according to any one of claims 1 to 9,

wherein an amount of the resin having a biphenyl skeleton and the (meth)acrylic monomer is 3 mass% or more and 20 mass% or less with respect to the entire thermally conductive paste.

11. The thermally conductive paste according to any one of claims 1 to 10,

wherein an amount of the (meth)acrylic monomer is 30 mass% or more and 95 mass% or less with respect to 100 mass% of a total amount of the resin having a biphenyl skeleton and the (meth)acrylic monomer.

12. The thermally conductive paste according to any one of claims 1 to 11,

wherein the thermally conductive paste contains a reactive diluent.

13. The thermally conductive paste according to claim 12, wherein an amount of the reactive diluent in the thermally conductive paste is 3 mass% or more and 20 mass% or less.

14. The thermally conductive paste according to any one of claims

1 to 13,

wherein the thermally conductive paste contains a curing accelerator.

15. An electronic device comprising:

a cured product of the thermally conductive paste according to any one of claims 1 to 14.